



Model ID		NPM-W2					
Front head	Rear head	Lightweight 16-nozzle head	12-nozzle head	Lightweight 8-nozzle head	3-nozzle head V2	Dispensing head	No head
Lightweight 16-nozzle head	12-nozzle head	NM-EJM7D				NM-EJM7D-MD	NM-EJM7D
Lightweight 8-nozzle head	3-nozzle head V2	NM-EJM7D-MD					NM-EJM7D-D
Dispensing head	Inspection head	NM-EJM7D-MA					NM-EJM7D-A
No head		NM-EJM7D				NM-EJM7D-D	
PCB dimensions	Single-lane *1	Batch mounting	L 50 mm × W 50 mm ~ L 750 mm × W 550 mm		2-positin mounting	L 50 mm × W 50 mm ~ L 350 mm × W 550 mm	
	Dual-lane *1	Dual transfer (Batch)	L 50 mm × W 50 mm ~ L 750 mm × W 260 mm		Dual transfer (2-positin)	L 50 mm × W 50 mm ~ L 350 mm × W 260 mm	
		Single transfer (Batch)	L 50 mm × W 50 mm ~ L 750 mm × W 510 mm		Single transfer (2-positin)	L 50 mm × W 50 mm ~ L 350 mm × W 510 mm	
Electric source		3-phase AC 200, 220, 380, 400, 420, 480 V 2.8 kVA					
Pneumatic source *2		0.5 MPa, 200 L / min (A.N.R.)					
Dimensions *2		W 1 280 mm *3 × D 2 332 mm *4 × H 1 444 mm *5					
Mass		2 470 kg (Only for main body: This differs depending on the option configuration.)					
Placement head		Lightweight 16-nozzle head (Per head)		12-nozzle head (Per head)		Lightweight 8-nozzle head (Per head)	3-nozzle head V2 (Per head)
		High production mode[ON]	High production mode[OFF]	High production mode[ON]	High production mode[OFF]		
Max. speed		38 500 cph (0.094 s / chip)	35 000 cph (0.103 s / chip)	32 250 cph (0.112 s / chip)	31 250 cph (0.115 s / chip)	20 800 cph (0.173 s / chip)	8 320 cph (0.433 s / chip) 6 500 cph (0.554 s / QFP)
Placement accuracy (Cpk ≥ 1)		± 40 μm / chip	± 30 μm / chip (± 25 μm / chip *6)	± 40 μm / chip	± 30 μm / chip	± 30 μm / chip ± 30 μm / QFP □12 mm ~ □32 mm ± 50 μm / QFP □12 mm Under	± 30 μm / QFP
Component dimensions (mm)		0402 *7 chip ~ L 6 × W 6 × T 3	03015 *7 *8 / 0402 *7 chip ~ L 6 × W 6 × T 3	0402 *7 chip ~ L 12 × W 12 × T 6.5		0402 *7 chip ~ L 32 × W 32 × T 12	0603 chip to L 150 × W 25 (diagonal 152) × T 30
	Component supply	Taping	Tape : 4 / 8 / 12 / 16 / 24 / 32 / 44 / 56 mm			Tape : 4 to 56 mm	Tape : 4 to 56 / 72 / 88 / 104 mm
	Stick	Max.120(Tape : 4, 8 mm)				Front/rear feeder cart specifications : Max.120 (Tape width and feeder are subject to the conditions on the left) Single tray specifications : Max.86 (Tape width and feeder are subject to the conditions on the left) Twin tray specifications : Max.60 (Tape width and feeder are subject to the conditions on the left)	
	Tray					Front/rear feeder cart specifications : Max.30 (Single stick feeder) Single tray specifications : Max.21 (Single stick feeder) Twin tray specifications : Max.15 (Single stick feeder)	
						Single tray specifications : Max.20 Twin tray specifications : Max.40	
Dispensing head		Dot dispensing			Draw dispensing		
Dispensing speed		0.16 s / dot (Condition : XY=10 mm, Z=less than 4 mm movement, No θ rotation)			4.25 s / component (Condition : 30 mm x 30 mm corner dispensing) *9		
Adhesive position accuracy (Cpk ≥ 1)		± 75 μm / dot			± 100 μm / component		
Applicable components		1608 chip to SOP, PLCC, QFP, Connector, BGA, CSP			BGA, CSP		
Inspection head		2D inspection head(A)			2D inspection head(B)		
Resolution		18 μm			9 μm		
View size		44.4 mm × 37.2 mm			21.1 mm × 17.6 mm		
Inspection processing time	Solder Inspection *10	0.35 s / View size					
	Component Inspection *10	0.5 s / View size					
Inspection object	Solder Inspection *10	Chip component : 100 μm × 150 μm or more (0603 or more) Package component : φ150 μm or more			Chip component : 80 μm × 120 μm or more (0402 or more) Package component : φ120 μm or more		
	Component Inspection *10	Square chip (0603 or more), SOP, QFP (a pitch of 0.4 mm or more), CSP, BGA, Aluminum electrolysis capacitor, Volume, Trimmer, Coil, Connector *11			Square chip (0402 or more), SOP, QFP (a pitch of 0.3 mm or more), CSP, BGA, Aluminum electrolysis capacitor, Volume, Trimmer, Coil, Connector *11		
Inspection items	Solder Inspection *10	Oozing, blur, misalignment, abnormal shape, bridging					
	Component Inspection *10	Missing, shift, flipping, polarity, foreign object inspection *12					
Inspection position accuracy (Cpk ≥ 1) *13		± s20 μm			± 10 μm		
No. of inspection	Solder Inspection *10	Max. 30 000 pcs. / machine (No. of components : Max. 10 000 pcs. / machine)					
	Component Inspection *10	Max. 10 000 pcs. / machine					

\* Placement tact time, inspection time and accuracy values may differ slightly depending on conditions  
 \*4 : Dimension D including tray feeder : 2 570 mm  
 \*10 : One head cannot handle solder inspection and component inspection at the same time.  
 \*11 : Please refer to the specification booklet for details.  
 \*12 : Foreign object is available to chip components. (Excluding 03015 mm chip)  
 \*13 : This is the solder inspection position accuracy measured by our reference using our glass PCB for plane calibration. It may be affected by sudden change of ambient temperature.  
 \*5 : Excluding the monitor, signal tower and ceiling fan cover.  
 \*6 : ± 25 μm placement support option. (Under conditions specified by Panasonic)  
 \*7 : The 03015/0402 chip requires a specific nozzle/feeder.  
 \*8 : Support for 03015 mm chip placement is optional. (Under conditions specified by Panasonic : Placement accuracy ± 30 μm / chip)  
 \*9 : A PCB height measurement time of 0.5 s is included.

### ⚠ Safety Cautions

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

**Panasonic Group products are built with the environment in mind.** Please check the homepage for the details. [panasonic.com/global/corporate/sustainability](https://panasonic.com/global/corporate/sustainability)

Inquiries...	<b>Panasonic Connect Co., Ltd.</b> Process Automation Business Division  3-1-1 Inazu-cho, Toyonaka City, Osaka 561-0854, Japan  All data as of April 1, 2022 Ver. April 1, 2022  <small>© Panasonic Connect Co., Ltd. 2022</small>
--------------	---

# NPM

NEXT PRODUCTION MODULAR

## Manufacturing Process Innovation



# Model ID NPM-W2

- Model No. NM-EJM7D
- Model No. NM-EJM7D-MD    Model No. NM-EJM7D-D
- Model No. NM-EJM7D-MA    Model No. NM-EJM7D-A

\*Photograph is NM-EJM7D



● Changes in specifications and appearance may be made without notice for product improvement.  
 ● Please contact us via our website at <https://industrial.panasonic.com/ww/r/fw>

## 1 Higher productivity and quality with printing, placement and inspection process integration

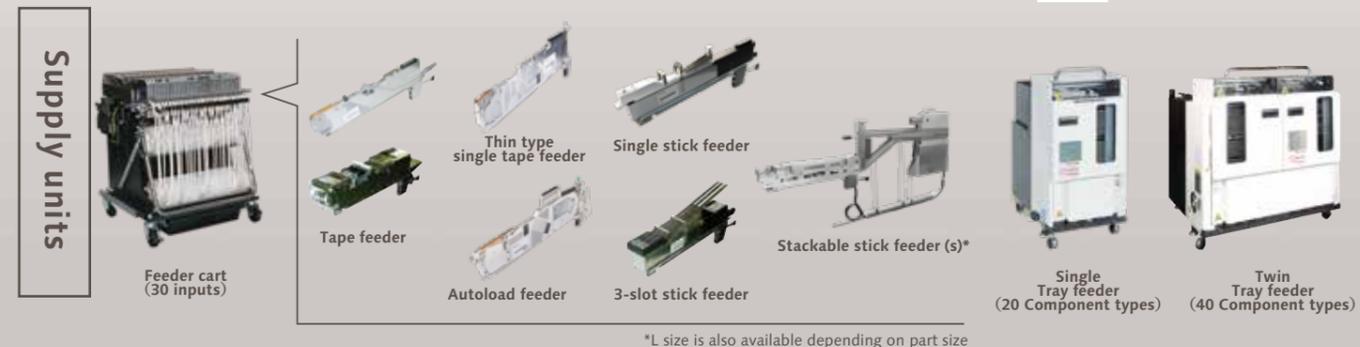
Depending on the PCB you produce, you can select High-speed mode or High-accuracy mode.

## 2 For larger boards and larger components

PCBs up to a size of 750 × 550 mm with component range up to L 150 × W 25 × T 30 mm

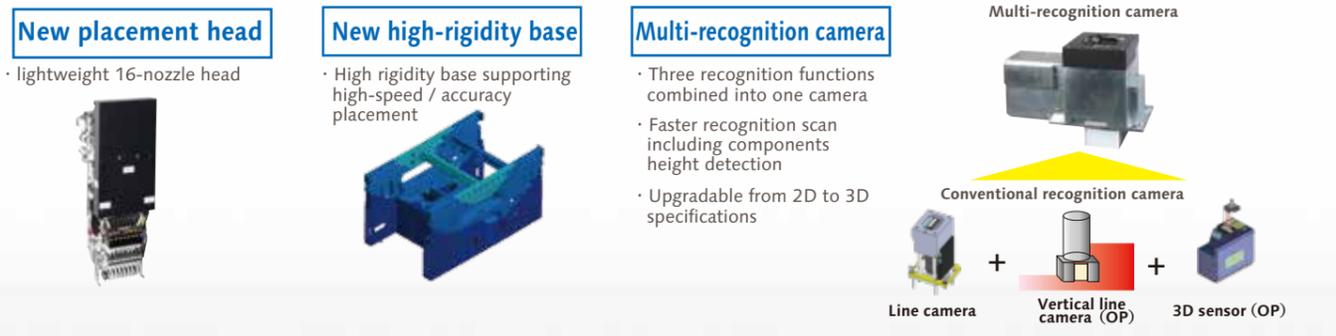
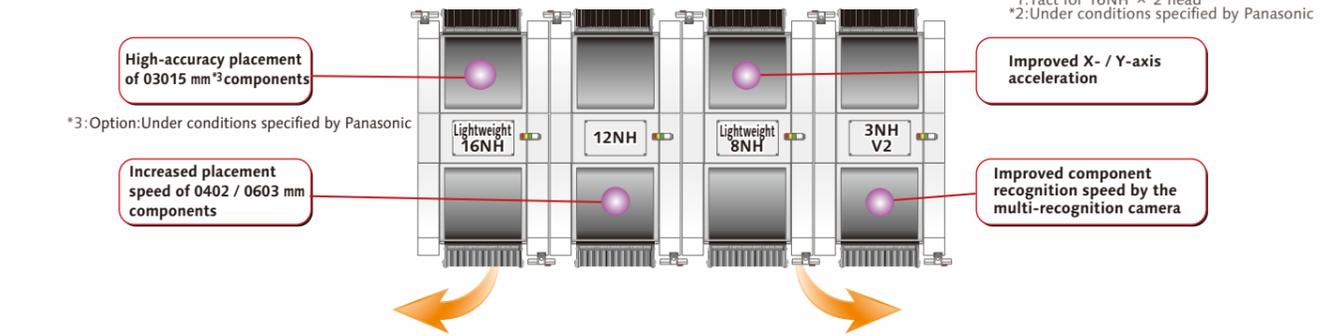
## 3 Higher area productivity through dual lane placement

Depending on the PCB you produce, you can select an optimal placement mode – "Independent" "Alternate" or "Hybrid"

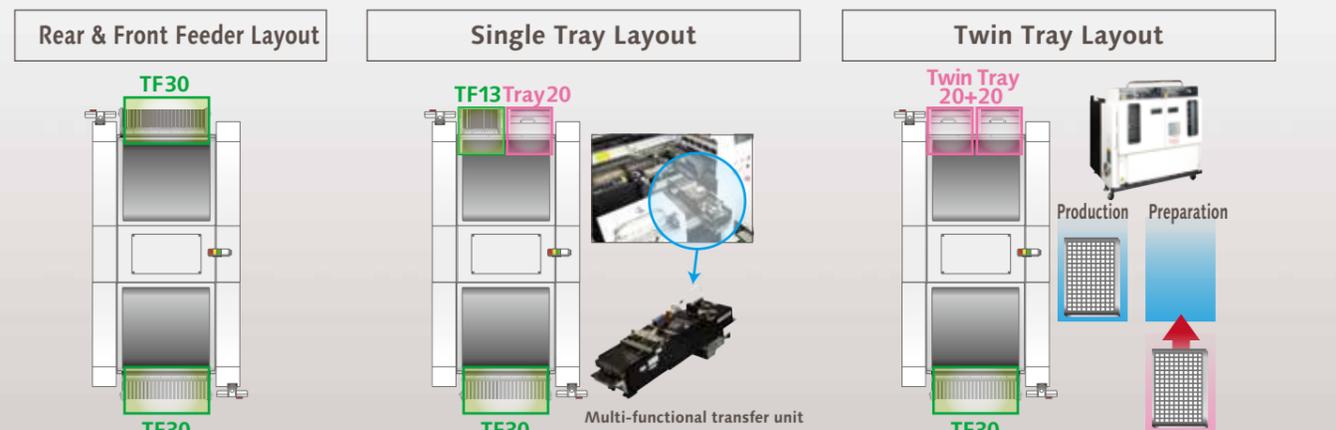


## Features Simultaneous realization of high area productivity and high-accuracy placement

- ◆ **High production mode** (High production mode: ON)  
Max. speed: 77 000 cph\*1 (IPC9850 (1608) : 59 200 cph\*1) / Placement accuracy: ± 40 μm
- ◆ **High accuracy mode** (High production mode: OFF)  
Max. speed : 70 000 cph\*1 / Placement accuracy : ± 30 μm (Option : ± 25 μm\*2)



## Machine Configuration



60 different components can be mounted from 16mm tape feeders.

13 fixed feeder slots are available. PoP tray mounting is possible via a transfer unit.

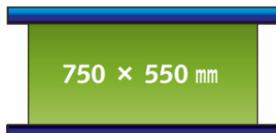
While one tray is used for production, the other tray can simultaneously be used to setup the next production in advance.



### Versatility

#### Large Board

Single-lane specifications (Selection spec.)



Large Board up to 750 x 550 mm can be handled

Dual-lane specifications (Selection spec.)



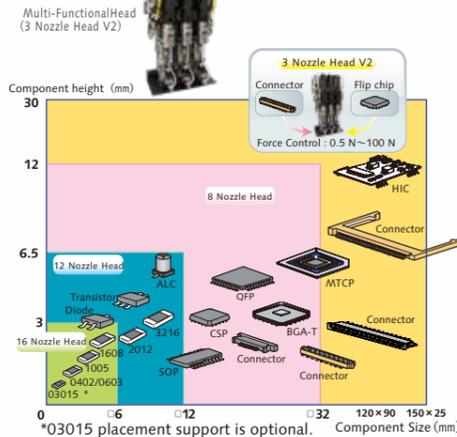
Large boards (750 x 260 mm) can be handled collectively. Boards (up to a size of 750 x 510 mm) can be handled collectively during single transfer.

#### Large Components

Compatible to component sizes up to 150 x 25 mm

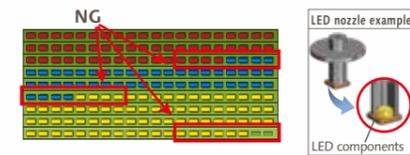


Max. placement load 100 N



### LED Placement

#### Brightness Binning



Avoid mixing of brightness and minimizes component and block disposal. Monitors remaining component count to avoid component exhaust during operation.

\*Please ask us for nozzles that support LED components of various shapes

#### Other functions

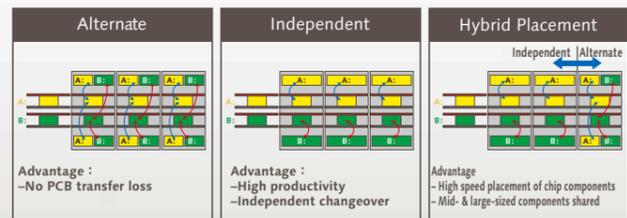
- Global bad mark recognition function
- Reduces in travel/recognition time to recognize bad marks
- PCB standby between machines (with the extension conveyor attached)
- Minimizes the PCB (750 mm) change time

### High productivity Employs dual mounting method

#### Alternate, Independent & Hybrid Placement

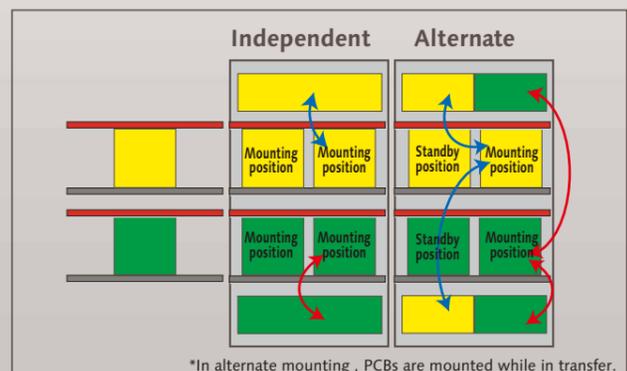
Selectable "Alternate" and "Independent" dual placement method allows you to make good use of each advantage.

- Alternate: Front and rear heads execute placement on PCBs in front and rear lanes alternately.
- Independent: Front head executes placement on PCB in front lane and rear head execute placement on rear lane.



#### PCB exchange time reduction

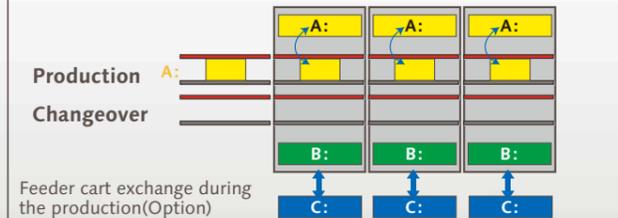
Two PCBs can be clamped on one stage (PCB length: 350 mm or less). And Higher productivity can be realized by reducing PCB exchange time.



\*In alternate mounting, PCBs are mounted while in transfer.

#### Independent changeover

In the independent mode, you can conduct a changeover on one lane while production continues on the other lane. You can exchange the feeder cart during the production also with Independent changeover unit (option). It supports automatic support pin replacement (option) and an automatic changeover (option) so that it provides the best changeover for your production type.



#### Automatic replacement of support pins (option)

Automate position change of support pins to enable non-stop changeover and help save man-power and operation errors.

### Quality improvement

#### Placement height control function

Based on PCB warpage condition data and thickness data of each of the components to be placed, the control of placement height is optimized to improve mounting quality.

### Operating rate improvement

#### Feeder location free

Within same table, feeders can be set anywhere. Alternate allocation as well as setting of new feeders for next production can be done while the machine is in operation.

Feeders will require off-line data input by support station (option).

### Solder Inspection (SPI) · Component Inspection (AOI) Inspection head

#### Solder Inspection

Solder appearance inspection

Oozing	OK	NG
blur	OK	NG
misalignment	OK	NG
abnormal shape	OK	NG
bridging	OK	NG

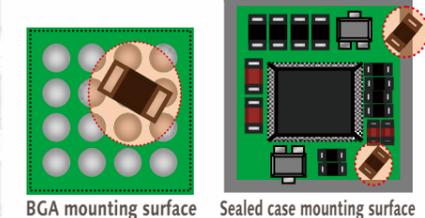
#### Mounted component Inspection

Appearance inspection of mounted components

Missing	OK	NG
shift	OK	NG
flipping	OK	NG
polarity	OK	NG

#### Pre-mounting foreign object\*1 inspection

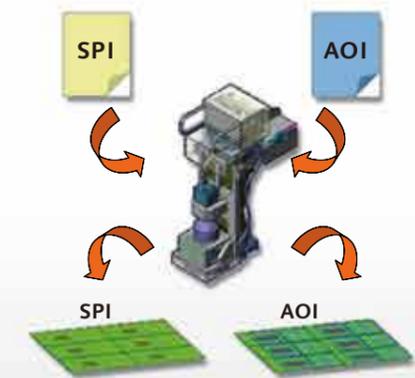
Pre-mounting foreign object inspection of BGAs  
Foreign object inspection right before sealed case placement



\*1: Foreign object is available to chip components.

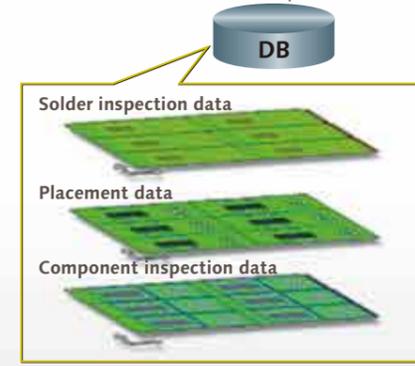
#### SPI and AOI automatic switching

Solder and component inspection is switched automatically according to production data.



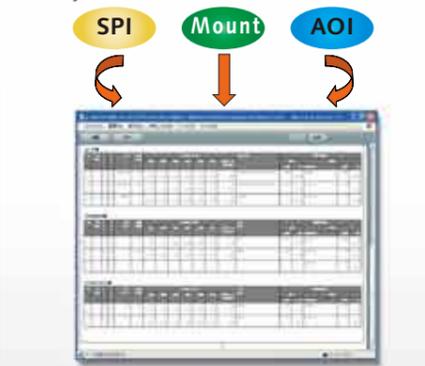
#### Unification of inspection and placement data

Centrally managed component library or coordinate data does not require two data maintenance of each process.



#### Automatic link to quality information

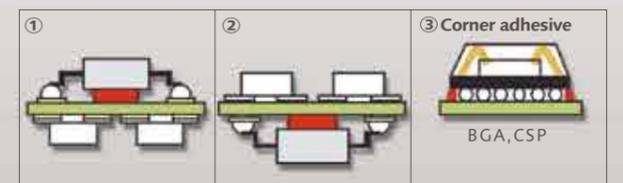
Automatically linked quality information of each process assists your defect cause analysis.



### Adhesive Dispensing Dispensing head

#### Screw-type discharge mechanism

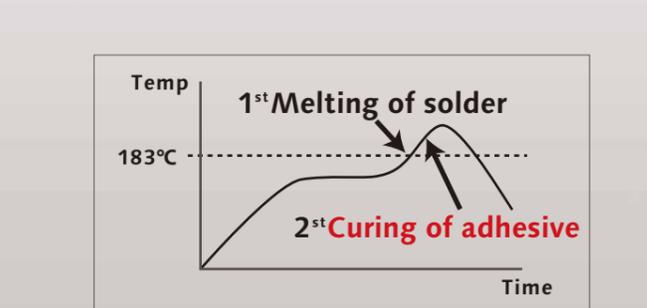
- Panasonic's NPM has the conventional HDF discharge mechanism, which ensures the high-quality dispensing.
- ① Misalignment prevention of the large-sized component at board transferring
- ② Drop prevention of the back side component at reflowing
- ③ Adhesive reinforcement of BGA and CSP\*



\* Pre-demonstration is required.

#### Self-Alignment Adhesive

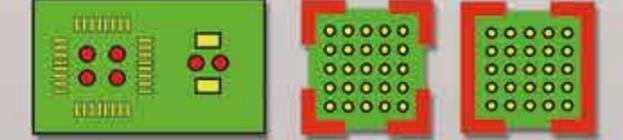
Our ADE 400D series is a high-temperature curing SMD adhesive with good component self-alignment effect. This adhesive is also suitable for use in SMT lines to fix bigger components.



After the solder melts, self-alignment and component sinking occurs.



#### Supports various dot/drawing dispensing patterns



High accuracy sensor (option) measures local PCB height to calibrate dispensing height, which allows for non-contact dispensing on PCB.

## High-quality placement

## APC system

Controls variations in PCBs and components, etc. on a line basis to achieve quality production.

### APC-FB \*1

#### Feedback to the printing machine

Based on the analyzed measurement data from solder inspections, it corrects printing positions. (X, Y, θ)

### APC-FF \*1

#### Feedforward to the placement machine

It analyzes solder position measurement data, and corrects component placement positions (X, Y, θ) accordingly.  
Chip components (0402C/R ~)  
Package component (QFP, BGA, CSP)

### APC-MFB2

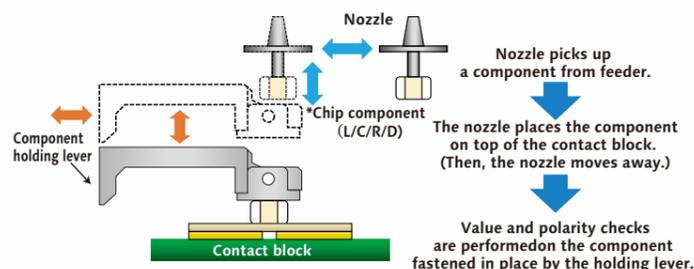
#### Feedforward to AOI / Feedback to the placement machine

Position inspection on APC offset position  
The system analyzes AOI component position measurement data, corrects placement position (X, Y, θ), and thereby maintains placement accuracy.  
Compatible with chip components, lower electrode components and lead components \*2

\*1: APC-FB (feedback)/FF (feedforward): 3D inspection machine of another company can be also connected. (Please ask your local sales representative for details.)  
\*2: APC-MFB2 (mounter feedback2): Applicable component types vary from one AOI vendor to another. (Please ask your local sales representative for details.)

## Misplacement prevention

## LCR checker option



At the start of production, or during component supply or product changeover, it checks mounted component values. This helps improve machine availability through a reduction in time spent on component checks, as well as preventing misplacement due to loading of components on wrong feeder, defective components, or mislabeled reels, and thereby contributes to manufacturing conforming items. In addition, since checked value data is output to a file on LNB (FA PC), you can subsequently use the data to keep track, for example, of any changes or histories of mounted components.

Component size	0402 ~ 6 mm
Component	Resistance, Capacitor, Inductor, Diode

## Component Verification option

Prevents setup errors during changeover Provides an increase of production efficiency through easy operation



- **Preemptively deters component misplacement**  
Prevents misplacement by verifying production data with the barcode information on changeover components.
- **Automatic setup data synching function**  
The machine itself does the verification, eliminating the need to select separate setup data.
- **Interlock function**  
Any problems or lapses in verification will stop the machine.
- **Navigation function**  
A navigation function to make the verification process more readily understandable.

\*Wireless scanners and other accessories to be provided by customer

## Off-line setup support station

With the support stations, offline feeder cart setup is possible even outside of the manufacturing floor.

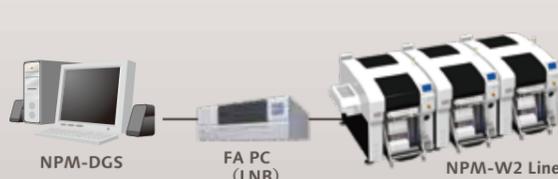
● **Two types of Support Stations are available.**

- ① **Component verification station**
  - Batch Exchange Cart Setup: Provides power to all feeders in cart.
  - Feeder setup: Provides power to individual feeders.
  - Component verification: Navigator that indicates any location where feeders need exchange.
- ② **Power supply station**  
The simpler type of station composed of the batch exchange cart setup and the feeder setup features.



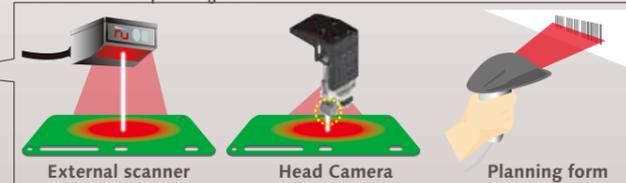
## Changeover ability

Supporting changeover (production data and rail width adjustment) can minimize time loss



## Automatic changeover option

● **PCB ID read-in type**  
PCB ID read-in function is selectable from among 3 types of external scanner, head camera or planning form



## Feeder setup navigator option

It is a support tool to navigate efficient setup procedure. The tool factors in the amount of time it takes to perform and complete setup operations when estimating the time required for production and providing the operator with setup instructions. This will visualize and streamline setup operations during setup for a production line.

- ① **Gross Production Time Estimate**  
Production completion time is estimated based on setup time and available human resource
- ② **Feeder preparation process instructions**  
Instructs cart/machine preparation process in three steps: load, remove, and relocate
- ③ **Instruction Display on Tablet Device**  
Instructions can be checked from anywhere

## Operating rate improvement

## Parts supply navigator option

A component supply support tool that navigates efficient component supply priorities. It considers the time left until component run-out and efficient path of operator movement to send component supply instructions to each operator. This achieves more efficient component supply.

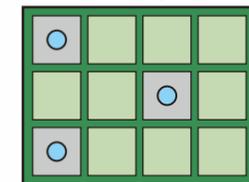
- ① **Wireless scanner indication of supply priorities**  
Considers the time left until component run-out and efficient path of operator movement to send supply priority instructions.
- ② **Visualization of supply statuses**  
Visualizes supply instructions sent to each operator on the main troubleshooting console.
- ③ **Cut down of redundant work and waiting times**  
Components are supplied per operator to prevent any overlaps.

\*PanaCIM is required to have operators in charge of supplying components to multiple production lines.

## PCB information communication function

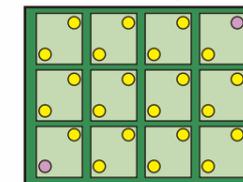
Information of mark recognitions done on first NPM machine in line is passed on to downstream NPM machines. Which can reduce cycle time utilizing the transferred information.

[Subject for communication]  
Bad mark recognition



Legend: Good (Green), Bad (Red)

Pattern mark recognition



Legend: Master mark (Yellow), All marks are recognized at the first machine and downstream machines only recognize master marks.

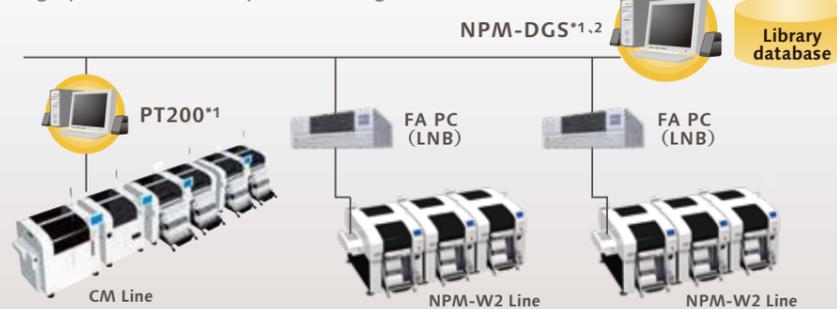


\*Please refer to "Specification" booklet for details.

## Data Creation System

## NPM-DGS (Model No. NM-EJS9A)

This is a software package that provides integrated management of component library and PCB data, as well as production data that maximizes mounting lines with high-performance and optimization algorithms.



\*1: A computer must be purchased separately.  
\*2: NPM-DGS has two management functions of floor and line level.

## Offline Camera (option)

Component data can be created offline even while the machine is in operation. Use the line camera to create component data. Lighting conditions and recognition speed can be confirmed in advance, so it contributes to the improvement of productivity and quality.



## DGS Automation (option)

Automated manual routine tasks reduce operation errors and data creation time. Manual routine tasks can be automated. By collaborating with the customer system, the routine tasks for creating data can be reduced, so it contributes to a significant reduction in production preparation time. It also includes the function to automatically correct the coordinates and angle of the mounting point (Virtual AOI).

Example of entire system image:

Automated tasks (excerpt):

- CAD import
- Offset mark setting
- PCB chamfering
- Mounting point misalignment correction
- Job creation
- Optimization
- PPD output
- Download

## Optimization of setup (option)

In production involving multiple models, setup workloads are taken into account and optimized. For more than one PCB sharing common component placement, multiple setups may be required due to a shortage of supply units. In order to reduce the required setup workloads in such a case, this option divides PCBs into similar component placement groups, selects a table(s) for setup and thus automates component placement operation. It contributes to improving setup performance and reducing production preparation time for customer manufacturing various kinds of products in small quantities.

